

特点

- 气味少
- 无卤板材有利于环境保护
- 高耐漏电起痕指数 600 伏以上
- 优异的耐湿、热性
- 适合之冲孔温度为 40~70℃
- 弓曲率、扭曲率小且稳定

Features

- Less odor
- Halogen-free, Friendly to the environment.
- High CTI over 600V
- Superior heat and humidity resistance
- Suitable for punching at 40~70℃
- Warpage and twist are small and stable.

General Properties 一般特性

Test Item 测试项目	Unit 单位	Test Condition 处理条件	Testing Method 测试方法	Specification 规格值	Typical Value 典型值
Solder Resistance 耐浸焊性 (260℃)	Sec	A	JIS C 6481	≥10	20~30
Heat Resistance 耐热性	—	130℃ 30min	JIS C 6481	No Change 无异常	No Change 无异常
Peel Strength (Copper Foil 35 μ m) 铜箔剥离强度 (35 μ m 铜箔)	kgf/cm	A 260℃ 10Sec	JIS C 6481	≥ 12	1.8~2.0 1.7~1.9
Flexural Strength 屈曲强度	Lengthwise 纵向	A	JIS C 6481	≥ 8	14~16
	Crosswise 横向			≥ 8	13~14
Volume Resistivity 体积阻抗系数	Ω-cm	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	5×10 ¹⁰ 5×10 ⁹	1.0×10 ¹² ~10 ¹³ 1.0×10 ¹² ~10 ¹³
Surface Resistivity 表面抗阻	Adhesive Side 粘接剂面	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	1×10 ¹² 1×10 ¹¹	1.0×10 ¹² ~10 ¹³ 1.0×10 ¹¹ ~10 ¹²
	Laminate Side 积层板面	C-96/20/65 C-96/20/65+C-96/40/90		1×10 ¹¹ 5×10 ⁸	1.0×10 ¹¹ ~10 ¹² 1.0×10 ¹⁰ ~10 ¹¹
Insulation Resistance 绝缘抗阻	Ω	C-96/20/65 C-96/20/65+D-2/100	JIS C 6481	1×10 ¹¹ 1×10 ⁸	1.0×10 ¹¹ ~10 ¹² 1.0×10 ⁹ ~10 ¹⁰
Chemical Resistance 耐化学性	—	3% NaOH 40℃ 3min 3%氢氧化钠 40℃3 分钟	JIS C 6481	No change 无异常	No Change 无异常
		Boiled in trichloroethylene for 3 min 三氯乙烯中煮沸 3 分钟	JIS C 6481	No change 无异常	No Change 无异常
Moisture Absorption 吸水率	%	E-24/50+D-24/23	JIS C 6481	≤0.75	0.5~0.75
Flammability 阻燃性	Rating	A	UL94	UL94 V-0	V-0
Dielectric Constant (1 MHz) 介电常数 (1 MHz)	—	C-96/20/65 C-96/20/65+D-24/23	JIS C 6481	≤5.0 ≤5.3	3.5~5.0 4.0~5.3
Dissipation Factor 介质损耗因子	—	C-96/20/65 C-96/20/65+D-24/23	JIS C 6481	≤0.04 ≤0.05	0.025~0.035 0.030~0.045
CTI Value CIT 值	V	0.1% NH ₄ CL	IEC 112	600	≥600
Punching Temperature 冲孔温度	℃	A	GB/T4722	40-70	40-70

Remarks: Typical values for reference only 注: 典型值仅作参考 Stand values according to JIS-C-6485 规格值参照 JIS-C-6485

A = Keep the specimen originally without any process 保持原样, 不作处理

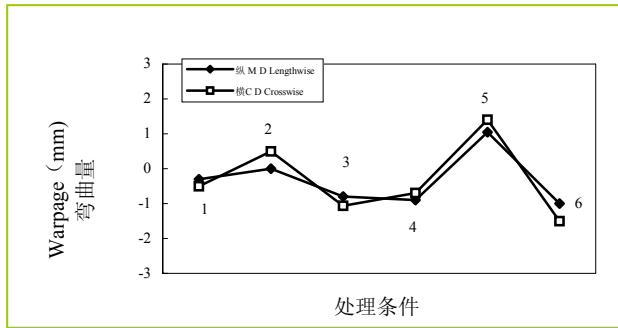
C = Temperature and humidity conditioning 在恒温恒湿的空气中处理

D = Immersing in distilled water with temperature control. 浸在恒温的水中处理

E = Temperature conditioning 在恒温的空气中处理

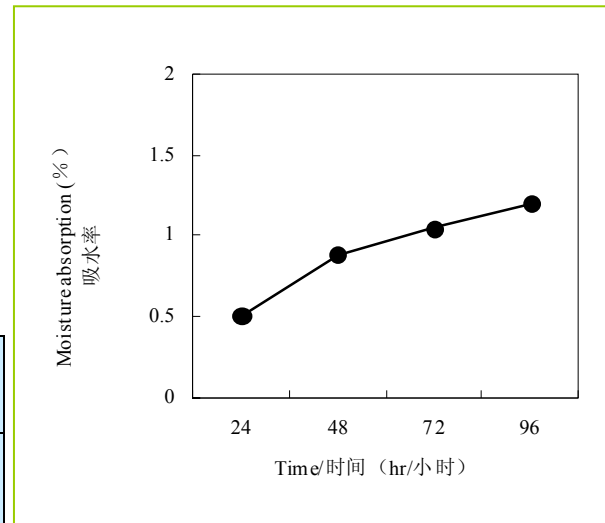
Speciality Chart 板材特性图

Warpage of PCB during processing/印制电路板
加工时弯曲度(Thickness 1.6mm single side)

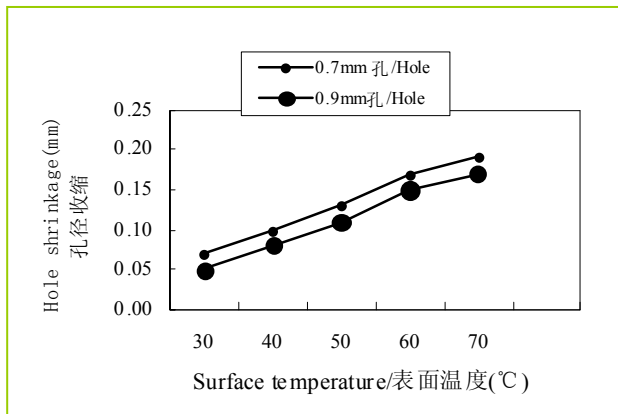


1.Feeding 投料	2.Heating at 130°C for 90 sec 130°C下加热 90 秒	3.Etching. Rinsing. Drying 蚀刻, 清洗, 烘干
4.Heating at 200°C for 30 sec 200°C下加热 30 秒	5.Punching at 50°C 50°C下冲孔	6.Soldering at 260°C for 5sec 260°C 焊锡 5 秒

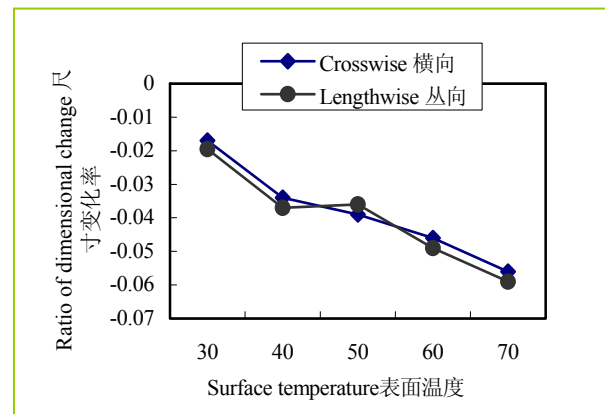
Moisture absorption 吸水率



Punched hole shrinkage
冲孔后孔径收缩



Dimensional change of punched PCB
冲孔后之尺寸变化



Purchasing Information 采购信息

Type 类型	Thickness 厚度	Copper Cladding 铜箔厚度	Regular Size (mm) 常规尺寸	CTI Value CTI 值
KB-2150GC	0.8mm ~	35μm	1020*1220mm (40" * 48")	600V
FR-2	1.6mm	70μm	1020*1020mm (40" * 40")	

Note: 1) Other sheet size and thickness could be available upon request. 可根据客户要求提供其它尺寸和厚度;

2) Speciality chart for reference only. 以上图表仅供参考;

3) Version updates without notice. 版本更新恕不另行通知。